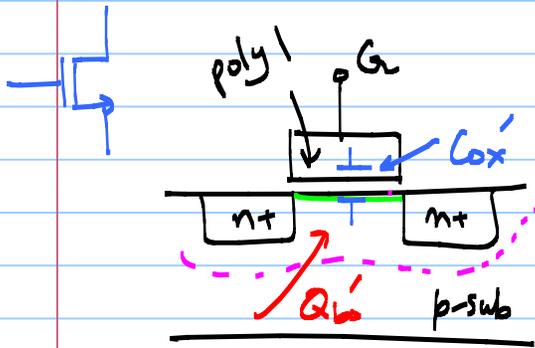


ECE 518 - Lecture 7

Note Title

2/12/2013



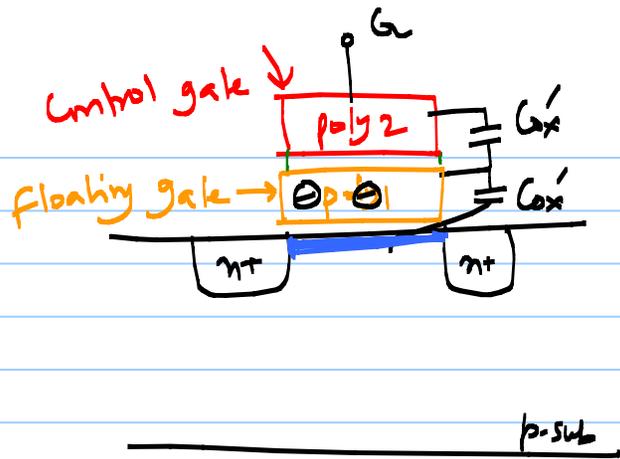
$$V_{THN} = -V_{ms} - 2V_{fp} + \frac{Q_{b'}}{C_{ox}}$$

\uparrow work function difference
 \uparrow $\phi(N_A)$

$$\phi = -V_{fp}$$

$$Q_{b'} = \sqrt{2q N_A \epsilon_{si} | -2V_{fp} |}$$

$$V_{THN} = -V_{ms} - 2V_{fp} + \frac{Q_{b'}}{C_{ox}}$$



$$\frac{C_x}{2C_x}$$

Erased device

$$\Rightarrow V_{TH, \text{erased}} = -V_{ms} - 2V_{fp} + \frac{2Q_{b0}'}{C_x}$$

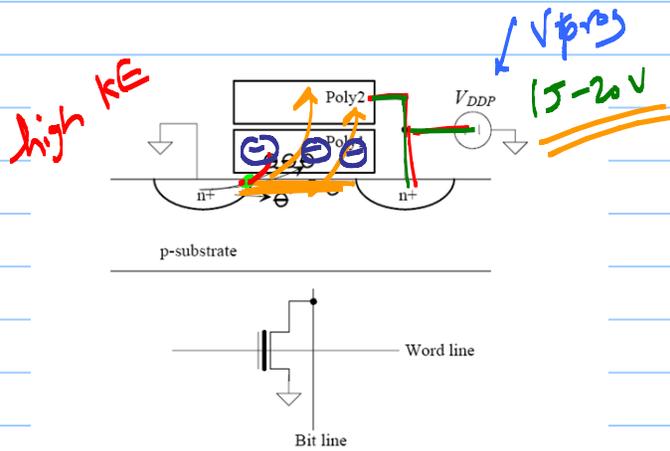
$$= \left(-V_{ms} - 2V_{fp} + \frac{Q_{b0}'}{C_x} \right) + \frac{Q_{b0}'}{C_x}$$

* trap e^- in poly 1 FG

$$V_{TH, \text{prog}} = -V_{ms} - 2V_{fp} + 2 \left[\frac{Q_{b0}'}{C_x} + \frac{|Q_{p-b1}|}{C_x} \right]$$

$\frac{Q_{b0}'}{C_x} \approx 50 \text{ mV}$ $t_{ox} = 100 \text{ \AA}$

EPRoM → Electrically programmable RoM



CHEI

channel hot electron injection

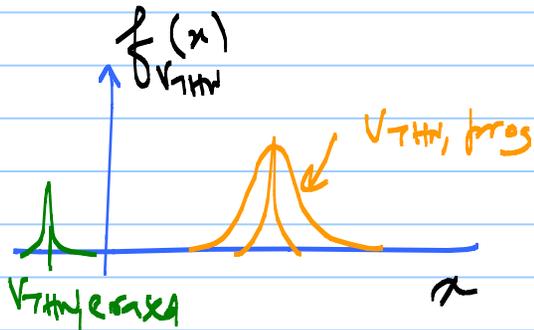
* lucky electron model

CHEI

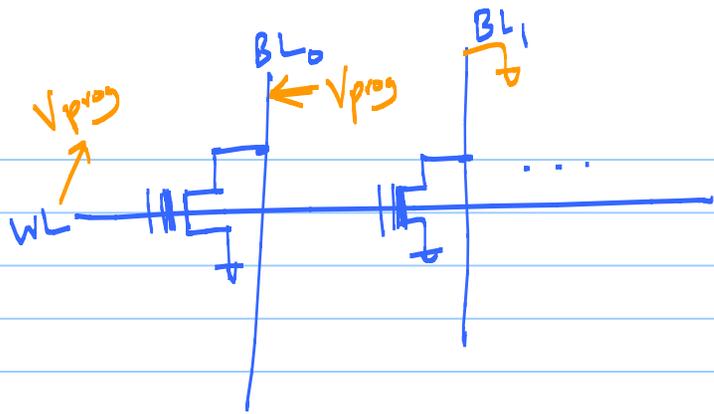
$$V_{prog} \Rightarrow V_{THN} \uparrow$$

$$I_D \downarrow$$

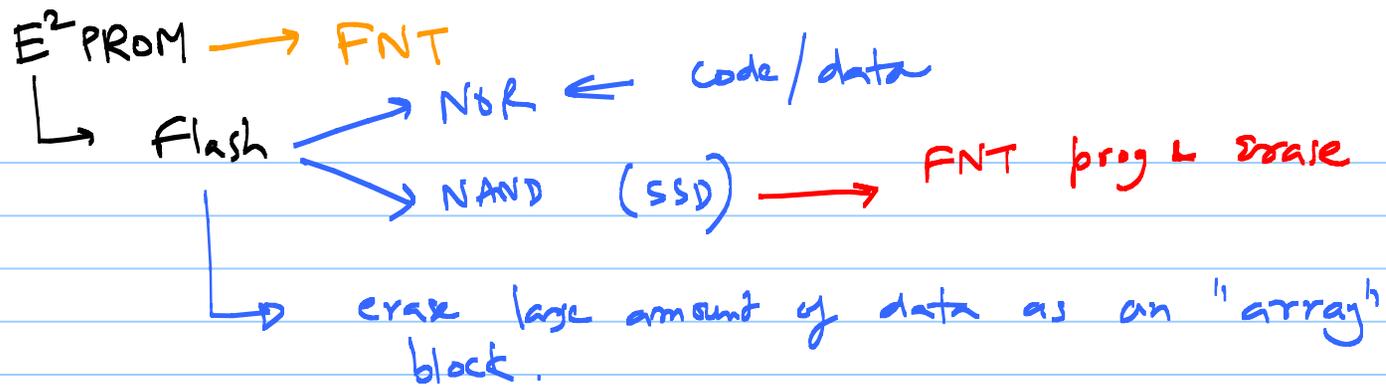
Figure 16.56 How charge is trapped on the floating gate using channel hot electron (CHE) injection.



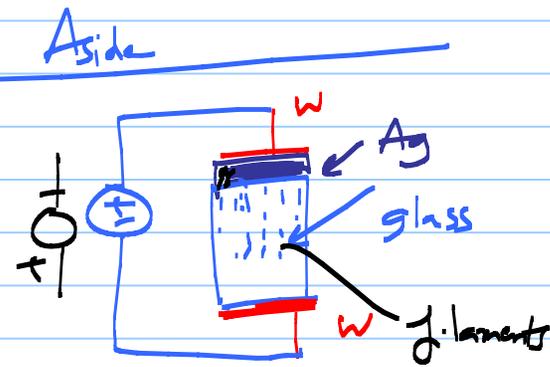
* self-limiting programming



* In a 1T1C1E, both drain and gate terminals need to be at a high voltage during programming.

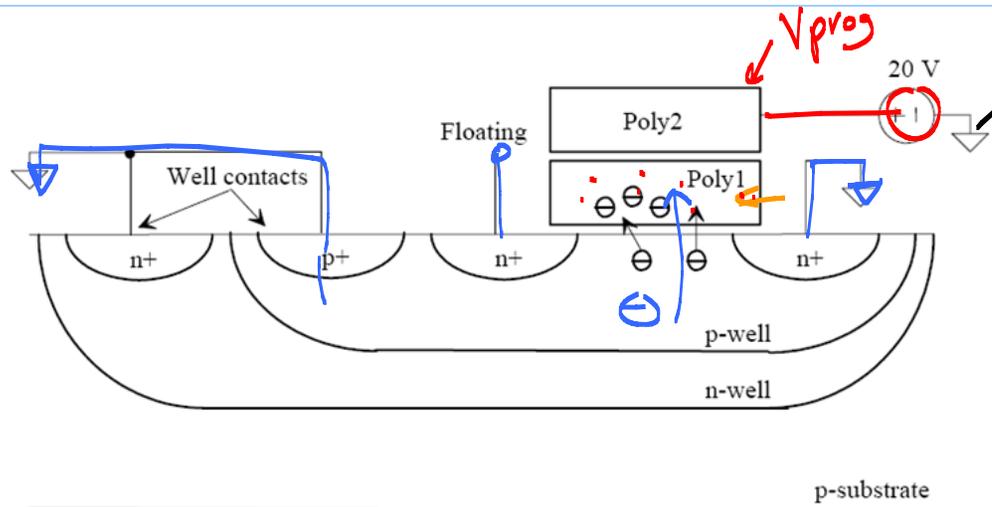


Fowler Nordheim Tunneling (FNT)



ion - conducting
chalcogenide
memories

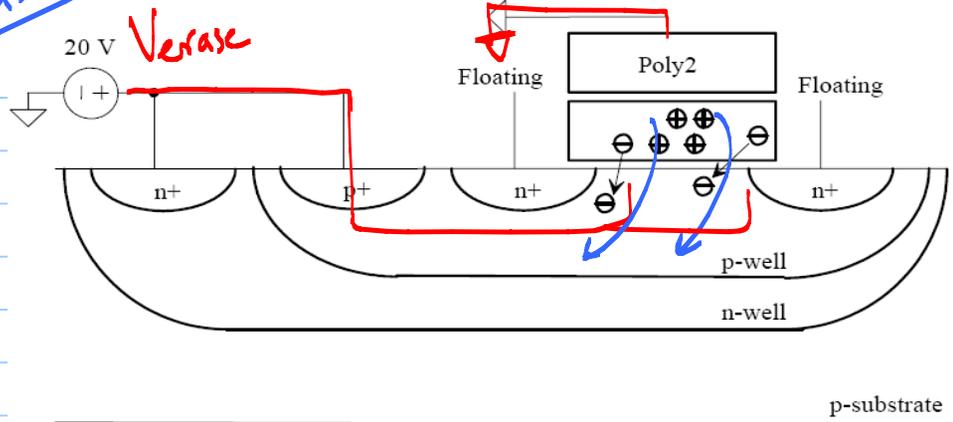
Programming



* triple-well process

Figure 16.58 FNT of electrons from the p-well to a floating gate to increase threshold voltage (showing programming).

Erase



FNT

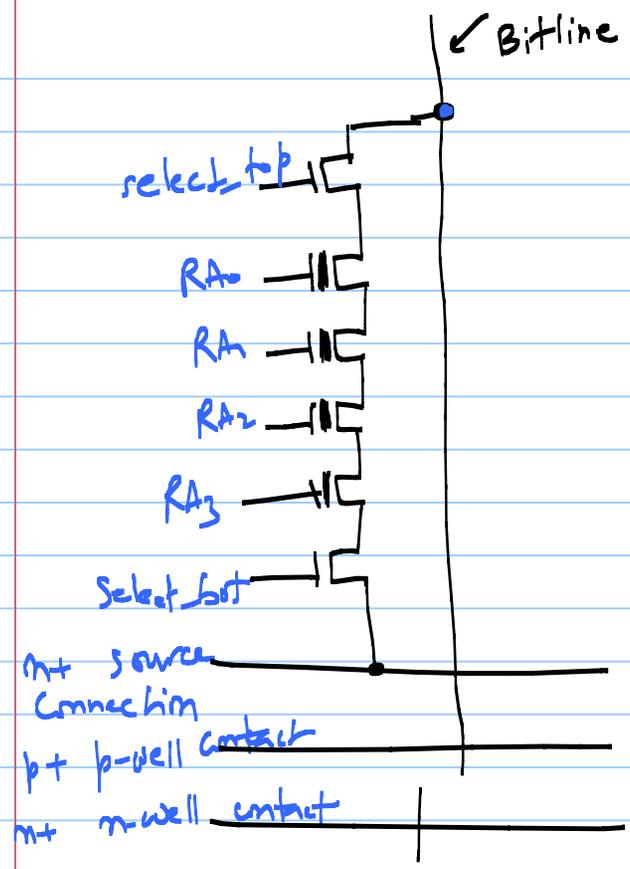
⇒ Over erase

Figure 16.59 FNT of electrons from the floating gate to p-well to decrease threshold voltage (showing erasing).

4-bit NAND

Bitline

"higher density"



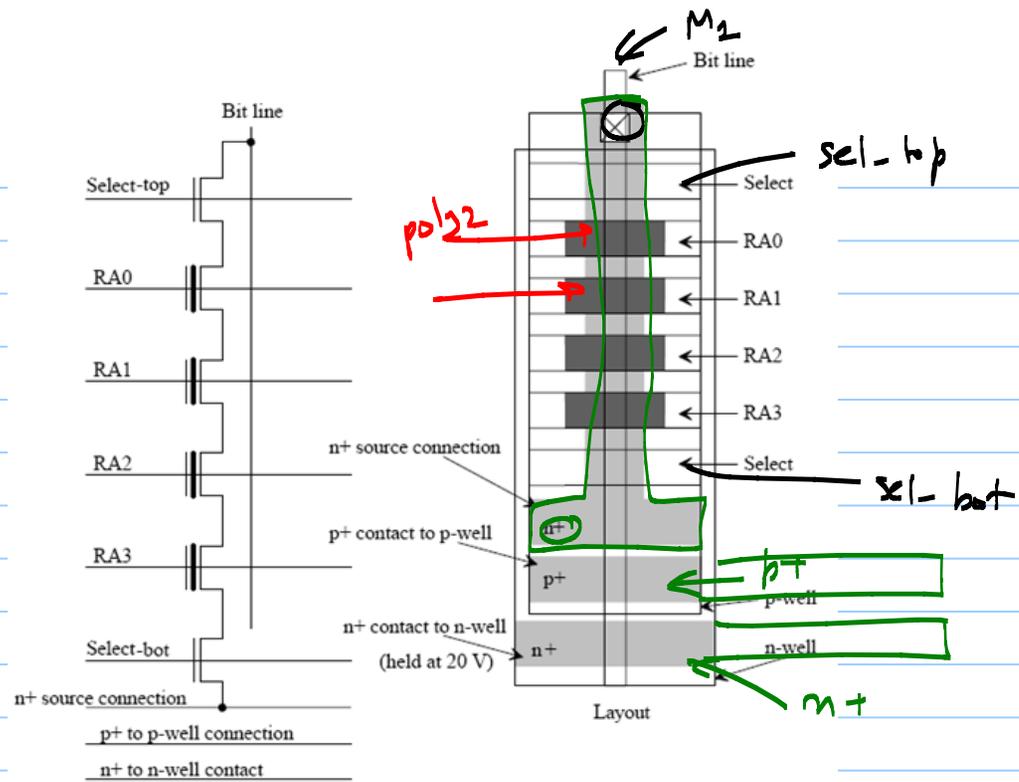
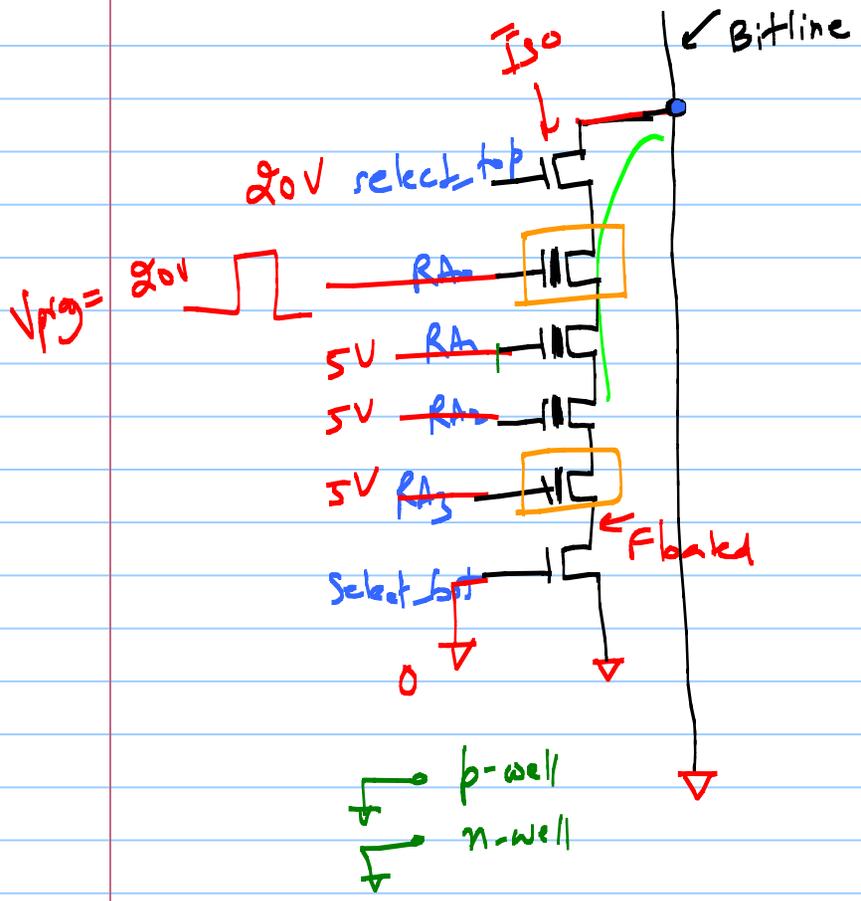


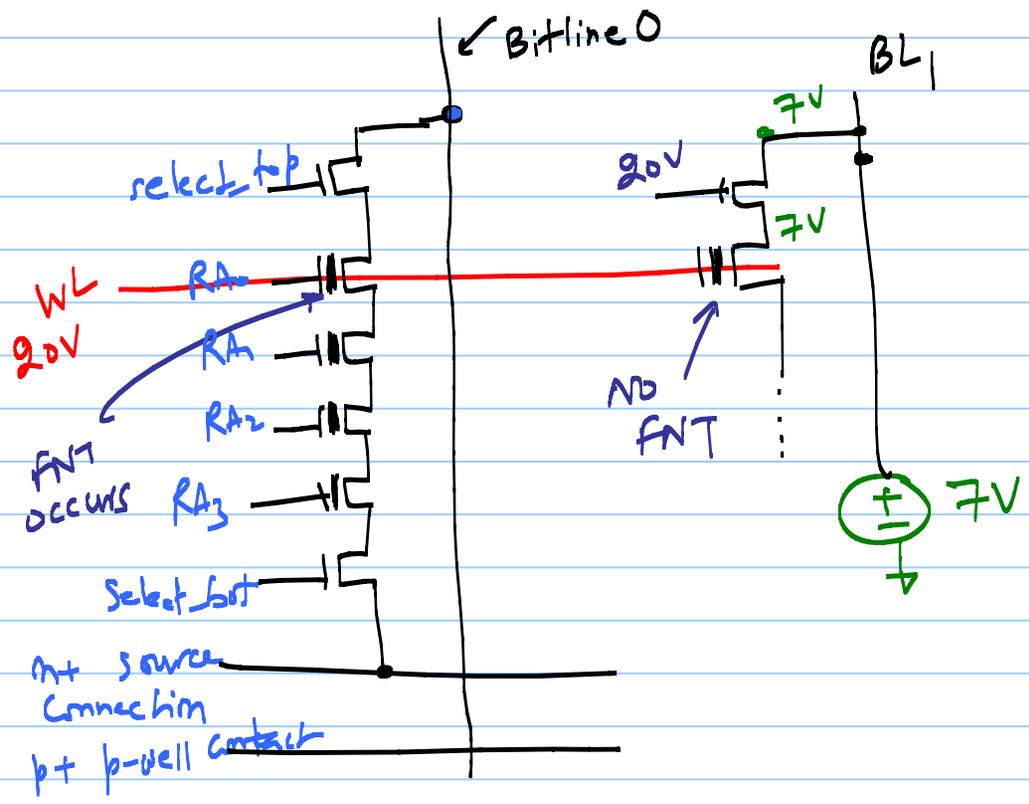
Figure 16.61 A 4-bit NAND Flash memory cell.

Program



"64-128 NAND String"

"Disturb"



Read

"ISO"

Bitline

5V select_{top}

2V

$V_{read} = 0V$

RA₀

5V RA₁

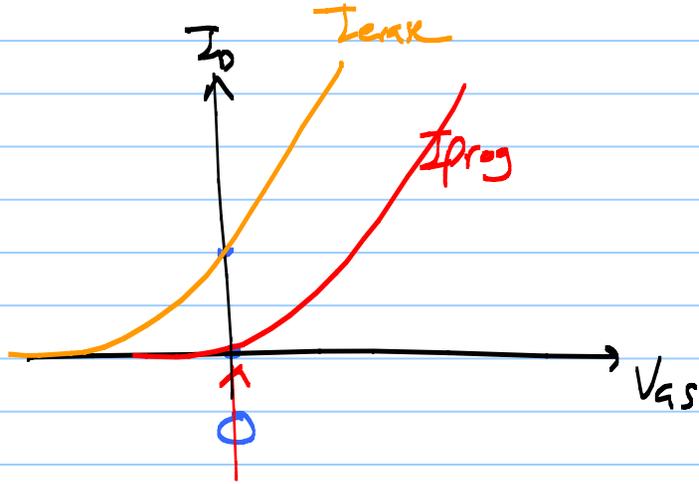
5V RA₂

5V RA₃

5V Select_{bot}

n+ source
connection

p+ p-well contact



Erase

